

Wafer Handling Product

Catalog







Vacuum Wand
Release Vacuum Wand
Bernoulli Chuck
BC Series

Small diaphragm vacuum pump FV Series

Manual Wand







$\operatorname{Vacuum} \operatorname{Wand} \mid$ Guarantee reliability for a long time

Realized improvement of work efficiency in wafer process

- Finely processed proprietary valve structure quarantees the stable performance for a long time in repetitious work to chuck and instantaneously release wafer.
- Mirror finished valve inside of wand exhibits superior airtightness and durability. Minimized particle generation when opening/closing button.
- Minimized exposure of metal part for safe handling.
- Chucking tip has highly mirror finished having surface prevents particle generation and maintains stable chucking surface precision even in use for a long time.
- The body is connected to tube by connector and so it is easy to remove from the tube.



Release Vacuum Wand | Propose new form of transfer

Vacuum Pump FV-W & Vacuum Wand

It's common for the conventional vacuum wand to chuck and transfer. Fluoro Mechanic added the blow-out function to securely place work in place.

Conductive for effective antistatic measures.

Vacuum Pump FV-10 & Vacuum Wand

Vacuum wand for transfer of small parts.



Bernoulli Chuck BC Series

For wafer transfer

Wrap with air and transfer gently

Bernoulli chuck generates highly strong suction power by jetting air utilizing the Bernoulli law. Wafer point-contacts the surface edge of Bernoulli chuck and is transferred by the stable holding power without rotating in non-contact condition at the wafer central part. It is designed usable for each wafer size with only a single body.



Small diaphragm vacuum pump FV Series | Easily usable but high performance

Proud of clean, noise reduction design

- Compact and high vacuum pressure
- Long service life and maintenance-free
- Clean discharge
- Noise reduction design for excellent calmness
- Flexible specification
- Cost performance



Manual Wand | Highly enhanced work efficiency

Manual Wand (Lever-Lock Series)

- Utilizing leverage, stable pinching force is sustained with less power.
- Release from labor to keep holding unlike manual wand.
- 2-point contact of pinching face minimizes contamination to wafer.

Manual Wand (L Series)

- •2-point contact minimizes contamination to wafer.
- Eliminates the potential of damage to wafer unlike conventional metal tweezers.
- Proprietary wafer stopper minimizes contact to wafer.

Manual Wand for High Temperature Application (H Series)

- Developed the method to securely bond SUS304 to Vespel. Thus, made pinching part thinner to prevent contact the adjoining wafre.
- Stable performance even under high temperature (288°C).

 And effective to prevent particle generation.







Transfer by power of the air Fluoro Mechanic



Wafer Handling Tools

Conductive C Series

Vacuum Wand

Chemical resistant | F Series

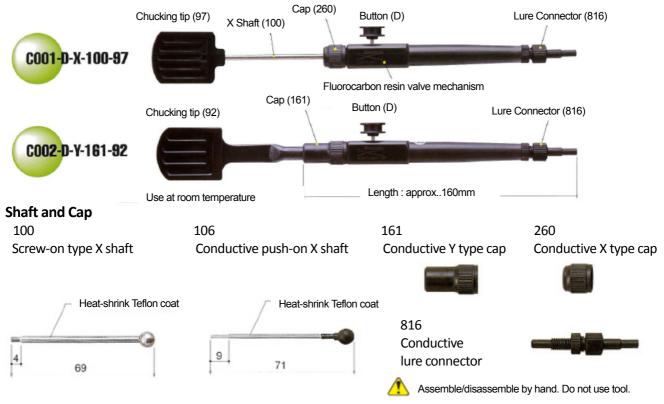
Promise reliability for a long time

Realized improvement of work efficiency in wafer process

- Finely processed proprietary valve structure promises the stable performance for a long time in repetitious work to chuck and instantaneously release wafer.
- Mirror finished valve inside of wand exhibits superior airtightness and durability.
 Minimized particle generation when opening/closing button.
- •Minimized exposure of metal part for safe handling.
- Chucking tip has highly mirror finished chucking surface prevents particle generation and maintains stable chucking surface precision even in use for a long time.
- The body is connected to tube by connector and so it is easy to remove from the tube.

Conductive

- •Material of the body is Nylon resin blended carbon fiber (TORAYCA) having superior physical properties and conductivity. The valve part is made of fluorocarbon resin and covered by Nylon blended carbon fiber by the unique molding method without impairing airtightness. Therefore, similarly to the conventional F series, the nimble opening/closing of valve is possible. (Patented)
- ullet Resistivity of the nylon connector connected to the rear part of the body is $10^{6\pm2}$.
- •Chucking tip is made of conductive PEEK blended carbon fiber having superior chemical resistance, heat resistance and resilience, heat-treated and mirror-finished after machining, thus maintains the stable performance even in use for a long time.
- Tips are selectable in various sizes corresponding to each wafer size.



Code	Description	Material		Compatible Tip Code											Conn	ection
No.	Description	iviaterial	90	91	92	95	96	97	98	99	64	67	68	69	Х	Υ
100	Screw-on X shaft	SUS						•							•	
106	Cond push-on X shaft	SUS + cond. Nylon				•	•								•	
161	Conductive Y type cap	conductive Nylon	•	•	•				•	•	•	•	•	•		•
260	Conductive X type cap	conductive Nylon				•	•	•							•	
816	Cond lure connector	conductive Nylon														

Conductive Spiral Tube



Code	Description	Material			Weight				
No.	Description	iviateriai	D1	D2	L1	L2	L3	L4	(g)
851-L	Conductive	Conductive	6	4	500	400	1000	1900	118
851-M	Spiral Tube	polyurethane elastomer	5	3	500	400	1000	1900	84

L1

L4

L2

Conductive PVC Tube

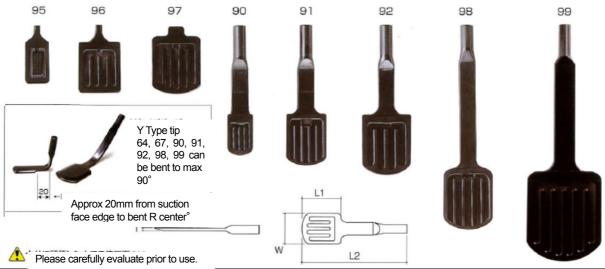


No.	Description	Material	Size (mm)	Weight (g)
852	Conductive PVC tube	PVC+SUS+conductive Nylon	1500	30

L3

D1 D2

Wafer Chucking Tip



	•									
Code	Description	Material	Sh	aft	Ca	ар		Size ((mm)	
No.	Description	iviateriai	100	106	161	260	Т	W	L1	L2
90	Conductive Y type tip for 5"				•		2.7	16	26	82
91	Conductive Y type tip for 6"				•		3	26	33	89
92	Conductive Y type tip for 8"				•		3	32	39	95
95	Conductive X type tip for 5"	Conductive		•		•	2.7	15	27	37
96	Conductive X type tip for 6"	PEEK		•		•	3	27	32	43
97	Conductive X type tip for 8"		•			•	3.7	31	37	43
98	Conductive Y type tip for 8"				•		3.5	31	39	129
99	Conductive Y type tip for 12"				•		3.5	48	58	148

Ideal for handling thin and fragile wafer!

Conductive Porous Tip•Ideal for reducing stress in handling compound semiconductor and thin wafer.

Nimble chucking and release response.

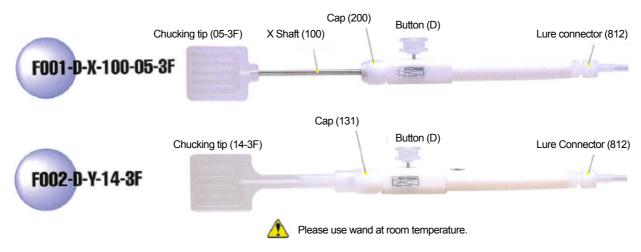
No.	Description	Material	Сар		Si	ze (mm)	(mm)			
NO.	Description	iviateriai	161	Т	W	L1	L2	φD		
64	Conductive porous tip for 3" - 5"		•	2.7	16	26	82	0.8		
66	Conductive porous tip for 8" – 12"	Conductive PEEK	•	3.5	48	58	151	0.8		
67	Conductive porous tip for 6" – 8"	, LLIK	•	3.5	31	39	129	0.8		



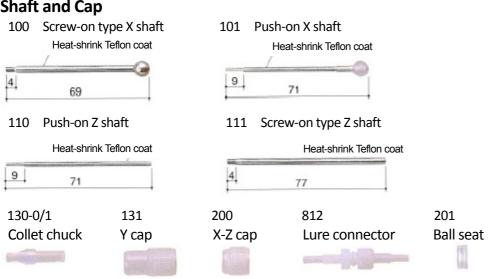
Chemical resistant

F Series Vacuum Wand

- ●The material of the body is fluorocarbon resin (4F-PTFE/3F-PCTFE). Precise process combining the superior properties of this material promises stable performance such as airtightness, durability for a long time.
- Cucking tip is made of 3F-PCTFE / PEEK / Vespel superior in chemical resistance, heat resistance, mechanical strength, heat-treated and mirror-finished after machining and maintains stable performance even in use for a long time.
- Chucking tip is selectable in various sizes and materials corresponding to each wafer size.

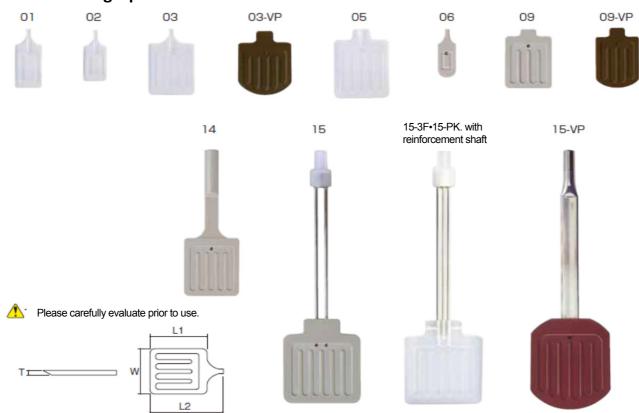


Shaft and Cap



Code	Description	Material				Com	patible	Tip Co	de				Co	nnectio	n
No.	Description	iviateriai	01	02	03	04	05	06	09	11	14	15	Х	Υ	Z
100	Screw-on type X shaft	SUS							•				•		
101	Push-on X shaft	SUS + 3F	•	•	•	•		•					•		
110	Push-On Z shaft	SUS	•	•	•	•		•							•
111	Screw-on type Z shaft	SUS					•		•						•
130-0	Collet chuck (\phi2.3)	3F	•	•	•	•		•							•
130-1	Collet chuck (\phi 3.4)	3F					•		•						•
131	Y type cap	3F								•	•			•	
200	X•Z type cap	3F	•	•	•	•	•	•	•				•		•
201	Ball seat	3F	•	•	•	•	•	•	•				•		
812	Lure connector	PFA													

Wafer Chucking Tip



Code	Description			X Shaft Z S			For X•Z type Shaf Cap		Y type cap	Size (mm)				
No.		3F	PK	VP	100	101	110	111	200	131	Т	W	L1	L2
01	X•Z type tip for 5"	•	•			•	•		•		2.7	15	26	35
02	X•Z type tip for 5"	•	•			•	•		•		2.7	13	21	30
03	X•Z type tip for 6"	•	•			•	•		•		2.7	26	31	40
03	X•Z type tip for 6"			•		•	•		•		2.7	30	31	38
05	X•Z type tip for 8"	•	•	•	•			•	•		3.8	31	35	41
06	X•Z type tip for 4"	•	•			•	•		•		2.6	10	21	30
09	X•Z type tip for 6"	•	•		•			•	•		3.8	26	31	37
09	X•Z type tip for 6"			•	•			•	•		3.8	26	33	38
14	Y type tip for 8"	•	•							•	3.1	31	34	86
15	Y type tip for 12"	•	•							•	3.5	47	55	162
15	Y type tip for 12"			•						•	3.0	51	61	180

Chucking Tip material sample



Information of material used for vacuum wand

4F-PTFE: Superior in chemical resistance, heat resistance and lubricity

3F-PCTFE : Less heat resistance and chemical resistance than PTFE, but Superior in mechanical Strength

PK-PEEK: Superior in chemical resistance, heat resistance and mechanical strength, but attacked by concentrated sulfuric acid

VP : Polyimide, DuPont's Vespel : Highest heat resistance in all resins, but affected by alkali Conductive nylon : Nylon 6 blended carbon fiber offers conductivity and tenacity, but affected by alkali

Conductive PEEK: PEEK blended carbon fiber, Superior in chemical resistance, heat resistance and mechanical strength, but attacked by concentrated sulfuric acid

PFA: Fluorocarbon resin having good moldability, and properties comparable to PTFE and PCTFE SS: Stainless steel (304)

Related Products

All materials of construction are conductive!

Conductive stand

Wall-mount Type *Fix by double side tape or M4 screw





677 For C001, C003





679

For C002

678



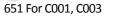
For C001, C003

Body code Code Description Material No. 002 001 003 677 Wall mount type stand (with tape) 678 Table-top stand Conductive nylon 679 Wall mount type stand for C•F002 (with tape) 680 Table-top stand for C•F002

Stand

Wall-mount Type *Fix by double side tape or M4 screw

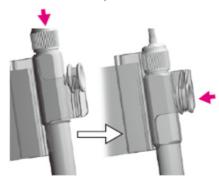




658 For C002, F002

679, 680, 658, 659 **Common Specifications**

For C002



Inserting C002 body into stand depresses button, shuts off and prevents waste of air



652 For C001, C003



Wall-mount Type

*Fix by double side tape or M4 screw



601

Table-top Type



Code	Description	Material	Body Code					
No.	Description	iviateriai	001	002	003			
651	Wall mount type stand (with tape)		•		•			
652	Table-top stand	Holder:	•		•			
658	Wall-mount type stand for C002•F002 (with tape)	Conductive nylon Base : Acrylic		•				
659	Table-top stand for C002•F002]		•				
601	Wall mount type stand (with tape)	0 1:-	•	•	•			
602	Table-top stand	Acrylic	•	•	•			

Related Products

- **●**Portable Tip Inspection Unit
- ●Inspect leak on tip when using wand.
- ●Light weight compact size. Usable anywhere.

●Body size: W60xL120xH45 (MM)

●Weight: 350g





※This gives rough estimate. Not product to be calibrated.

Precision Instrument. No impact!

●Lever-lock Manual Wand / Manual Wand

- ●2-point contact with wafer surface. Min. wafer contamination
- •Unique wafer stopper minimizes contact with wafer.
- ●Adhesive• metal free body washable and always kept clean. *Detailed catalog available.



Compact•High-Power

Small-size Diaphragm Vacuum Pump FV Series

- •Diaphragm depressurizing structure makes compact body and high vacuum pressure available.
- ●Long service life to theoretical value of durability of diaphragm.
- •HEPA filter for air intake and exhaust allows to use even in cleanroom. XFV-10 does not have HEPA filter.
- •Operating sound is very quiet due to the airtight body construction.
- •Usable anywhere if 100V outlet is available.
- •Provides superior performance in reliability, service life and power consumption. **Separate detailed catalog available.



Suction pressure variable by dial of the body.







Specifications

opcomoations									
Туре	For micro parts	General purpose	High vacuum	High flow					
Part No./Description	FV-10	FV-30	FV-60	FV-XP					
Rated voltage		100	VAC						
Power consumption	5.	0W	10.	0W					
Ultimate suction pressure	<-14kPa	<-50kPa	< -85kPa	< -60kPa					
Flow rate	2.8L/min	2.5L/min	2.5L/min	5.0L/min					
Size (mm)	155 x 72 x 54	137 x 88 x 85	137 x 8	8 x 133					
Weight (g)	600	800	12	50					
Durability	> 9000 hours								
Operation temperature	Max. 40°C								



Release Vacuum Wand Chucking•Blow-out Transfer System

Vacuum Pump FV-W & Vacuum Wand

It's common for the conventional vacuum wand to chuck and transfer.
Fluoro Mechanic added the blow-out function to securely place work in place.
Conductive for effective antistatic measures.

For transfer of small parts ••• Vacuum Wand Vacuum Pump FV-10 & Vacuum Wand

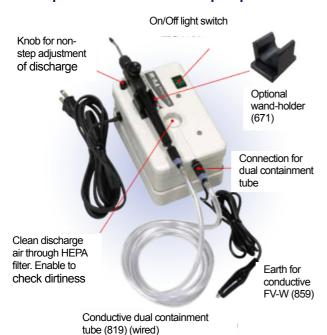


Release Vacuum Wand is • •

While transferring small part, that the object to be transferred does not part from the chucking part end due to airborne moisture or static electricity is often seen. There seem many cases disturbing work efficiency such as eventually applying impact to fall it off. What solves such problems is "Release Vacuum Wand" utilizing the industry's first blow-out function.

Release Vacuum Wand Specification

Composed of a set of vacuum pump FV-W and vacuum wand C007.



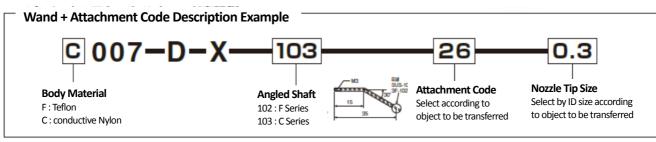
Pump

- One compact system for both suction and discharge operations.
- ●Both suction and discharge are viable with only one dual containment tube.

Comaninen	tuoc.	
Part No.	Conductive FV-W	FV-W
Description	Cond. 2-way pump	2-way pump
Rated voltage	100	VAC
Power consmp.	< 5	5.0W
Suction pres.	-33	3 kPa
Discharge pres.	0~	13 kPa
Flow rate	1.3L/min	(at no-load)
Size (mm)	137 x	88 x 85
Weight (g)	8	350
Durability	> 90	000 hrs
Accessories	Earth (859) Cond.dual containment tube (819)	Dual containment tube (820)

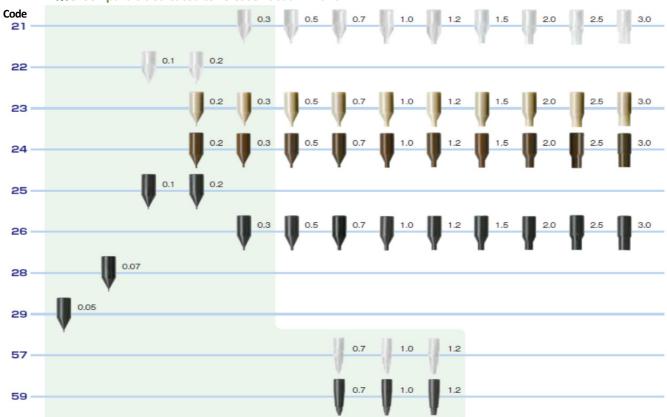




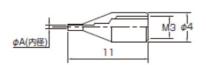


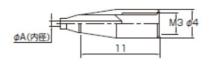
Applicable Nozzle Selectable from abundant lineup according to the work shape

XGreen part is dedicated to release vacuum wand.



								Outsi	ide Diar	neter						
C. I.	Description	A A a to dall	0.4	0.4	0.4	0.5	0.7	0.9	1.1	1.4	1.6	1.9	2.4	2.9	3.4	D d
Code	Description	Material				Insi	de Diar	neter (d)A) ※	Please	order b	y ID				Remark
			0.05	0.07	0.1	0.2	0.3	0.5	0.7	1.0	1.2	1.5	2.0	2.5	3.0	
21	3F nozzle	3F (PCTFE)					•	•	•	•	•	•	•	•	•	
22	3F nozzle with cap	3F (PCTFE)			•	•										
23	PEEK nozzle	PEEK				•	•	•	•	•	•	•	•	•	•	
24	Vespel nozzle	Vespel				•	•	•	•	•	•	•	•	•	•	Make to order
25	Cond PEEK nozzle with cap	Cond PEEK			•	•										
26	Cond PEEK nozzle	Cond PEEK					•	•	•	•	•	•	•	•	•	
28	Cond PEEK nozzle with cap	Conduct PEEK		•												
29	Cond PEEK nozzle with cap	Conduct PEEK	•													
57	Silicone rubber nozzle	Clear silicone rubber + 3F							•	•	•					OD slightly varies due to rubber
59	Cond Byton rubber nozzle	Cond Byton rubber + Cond PEEK							•	•	•					OD slightly varies due to rubber
	Custom-made nozzle			Nozzle available according to the objects to be chucked								Make to order				





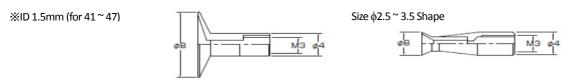
Shape of Code 57, 59

*All nozzles are made by machining.

Applicable Cup (Pad)



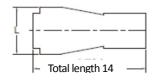
Code	Description	Material				Out	side Dia	ameter ((фВ)				Remark
Code	Description	Material	2.5	3.0	3.5	5.0	8.0	11	15	20	25	30	Кетагк
41	Silicone rubber pad	Silicone rubber	•	•	•	•	•	•	•				
42	Byton rubber pad	Byton reubber	•	•	•	•	•	•	•				
43	Conductive silicone pad	Silicone rubber + carbon	•	•	•	•	•	•	•				
44	Conductive Byton pad	Byton rubber + carbon	•	•	•	•	•	•	•				
45	Teflon pad	Teflon	•	•	•	•	•	•	•	•	•	•	
47	Complex curved surface chucking pad	Clear silicone rubber			•								



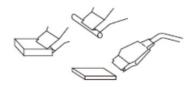
Applicable Slit Tip (Edge chucking tip)



Code	Description	Material	Size L (Length)			Remark
Code	Description	Material	3.0	4.5	6.0	Remaik
51	3F edge chucking tip	3F	•	•	•	
55	Conductive PEEK edge chucking tip	Nano-carbon PEEK	•	•	•	







Vacuum Wand Specification

Body with fluorocarbon resin valve covered

ultra-small parts easy to be affected by static

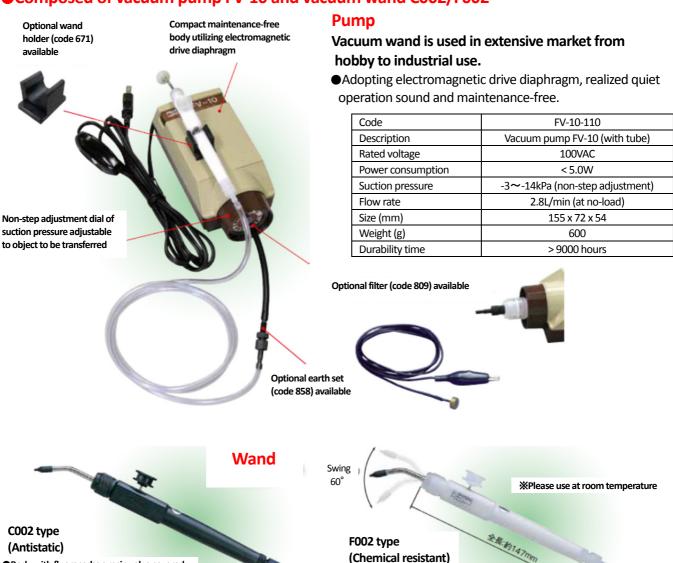
Option: Conductive PVC tube (code 852)

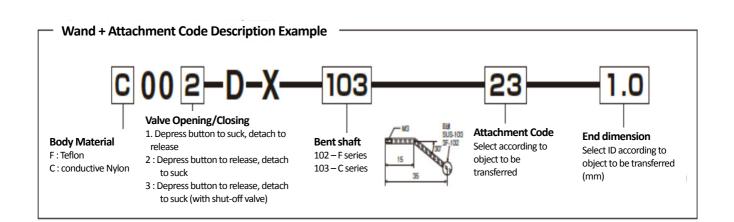
(wired) Length: 1.5m

by conductive nylon resin is ideal for

electricity (System resistivity : $10^6 \Omega$)

●Composed of vacuum pump FV-10 and vacuum wand C002/F002





●Mirror finished inside of fluorocarbon

valve exhibits superior airtightness, durability,

and maintains stable performance for a long time.

Small-size Diaphragm Vacuum Pump FV Series

- •Diaphragm depressurizing structure makes compact body and high vacuum pressure available.
- •Long service life to theoretical value of durability of diaphragm.
- ●HEPA filter for air intake and exhaust allows to use even in cleanroom.
- •Operating sound is very quiet due to the airtight body construction.
- •Usable anywhere if 100V outlet is available.
- •Provides superior performance in reliability, service life and power consumption.











Туре	General purpose	High vacuum	High flow	
Part No./Description	FV-30	FV-60 FV-X		
Rated voltage	100VAC			
Power consumption	5.0W	1	0.0W	
Ultimate suction pressure	<-50kPa	<-85kPa	<-60kPa	
Flow rate	2.5L/min 5.0L/			
Size (mm)	137 x 88 x 85	137 ×	(88 x 133	
Weight (g)	800	:	1250	
Durability		> 9000 hours		
Operation temperature		Max. 40°C		





Suction of corrosive gas, organic solvent, liquid, disassembling and impact cause malfunction. In this case, we do not assume any and all responsibility. In the event of failure, please send it to the maker.



Wrap with air and transfer gently

For wafer transfer

Bernoulli Chuck BC Series

Bernoulli chuck generates highly strong suction power by jetting air utilizing the Bernoulli law.

Wafer point-contacts the surface edge of Bernoulli chuck and is transferred by the stable holding power without rotating in non-contact condition at the wafer central part.

It is designed so that only a single body is usable for each wafer size.

Please watch video at www.furoro.jp



Feature

- •Usable for 2" to 12" wafer by selecting the handle angle of 20, 45 or 90 degree and changing to the guide ring for each wafer size. (As the use angle is the fixed angle, the use angle cannot be changed unless the body is changed.)
- As the guide stopper has gradual taper, it point-contacts the wafer edge.
- •The guide ring of ESD safe clear acrylic resin allows visual registration and suction condition check.
- •Conductive nylon resin is adopted for the body to make it lighter.
- •Capable of handling the thin wafer with printed pattern on both sides and of 50μm in thickness.
- Customized design available for the square or other type object.
- Button or lever switch selectable.

Product Outline

◆Select the body by the use angle of 20, 45 or 90. (See the belowpicture)
Usable for various wafers by changing the guide ring. Guide ring is easy to change.



Product Line-up

◆Wide variety of product line-up available for customers' requirements.

For horizontal wafer handling									
Wafer size	2"	3"	4"	5"	6"	8"			
Code No.	BC-K2	ВС-КЗ	BC-K4	BC-K5	вс-к6	BC-K8			
Material	Body: co	Body: conductive MC nylon, Guide ring: ESD safe PVC							
Air Pressure (MPa)	0	.1		0.2					
Weight	50g	70g	80g	100g	120g	170g			
Accessories	Conductive tube 6x4 (1.5m)								
Use angle	20°/45°/90°								



For horizontal wafer handling, below 300 micron								
Wafer size	6"	8"	12"					
Code No.	BC-K6-300	BC-K8-300	BC-K12-300					
Material	Body: conductive MC nylon, Guide ring: ESD safe PV							
Air Pressure (MPa)	0.15	0.2	0.3					
Weight	170g	220g	430g					
Accessories	sories Conductive tube 6x4 (1.5m)							
Use angle	20° / 45°							



For Protos Carrier, below 300 micron								
Wafer size	6"	8"	12"					
Code No.	BC-P6-300	BC-P8-300	BC-P12-300					
Material	Body: conductive MC nylon, Guide ring: ESD safe PVC							
Air Pressure (MPa)	0.15	0.2	0.3					
Weight	180g	240g	450g					
Accessories	Conductive tube 6x4 (1.5m)							
Use angle	45°							



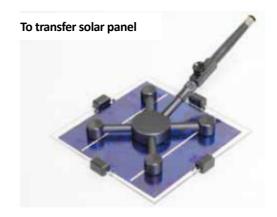
Option

◆Various options available for making Bernoulli Chuck BC Series more user-friendly.

• Guide Ring for square substrate

※Customized for desired size.





Dedicated filter

Filter for Bernoulli chuck with soft stopper.



Dedicated stand

For Bernoulli chuck for 2"~4" (Button type)
Code No. : 678



For Bernoulli chuck for vertical and horizontal carrier and for 2"~12"



For Bernoulli chuck for vertical and horizontal carrier (Lever type) Code No.: 698





Small Diaphragm Vacuum Pump

10 •30 •60• XP

FV Series

Concept derived from silent operation sound Light switch enables to visually check ON/OFF (excl. FV-10)

Compact and high vacuum pressure

Diaphragm is installed in airtight space, which enables multistep decompression. Realized compact body with the mechanism to obtain high vacuum pressure.

●Long service life and maintenance -free

Less mechanical abrasion and contact by electromagnetic drive. Maintenance is almost unnecessary. Long service life usable to theoretical value of durability of diaphragm.

Clean discharge

HEPA filter for air intake and exhaust allows to use even in cleanroom. Filter is visible through clear window of the body, which tells replacement time. (excl. FV-10)

Noise reduction design for excellent calmness

Operating sound is very quiet due to the airtight body construction. Compared with motor-drive type, no mechanical contact sound and calmness is maintained.

Flexible specification

No need of air source such as compressor, so usable anywhere if 100V outlet is available. Combining with our vacuum wand expands use purpose.

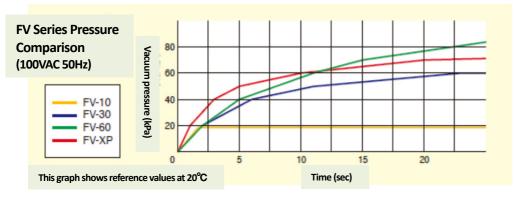
Cost performance

Simplified construction promises superior reliability, service life, power consumption compared with comparable vacuum pump. Inexpensive price can be offered.











Specifications

Туре	For micro parts	General purpose	High vacuum	High flow				
Part No./Description	FV-10	FV-30	FV-60	FV-XP				
Rated voltage		100VAC						
Power consumption	5.0	0W	10.0W					
Ultimate suction pressure	-3 ~< -14kPa	<-50kPa	< -85kPa	< -60kPa				
Flow rate	2.8L/min	2.5L/min	2.5L/min	5.0L/min				
Size (mm)	155 x 72 x 54	137 x 88 x 85	137 x 8	8 x 133				
Weight (g)	600	600 800						
Durability		> 9000	hours					
Operation temperature	ntion temperature Max.							



Suction of corrosive gas, organic solvent, liquid, disassembling and impact cause malfunction. In this case, we do not assume any and all responsibility. In the event of failure, please send it to the maker.



For wafer handling tool - - -

Extreme care is necessary for wafer handling. Scratch and stain, etc. are one of factors to be paid most attention while handling. Our manual wand is the product having new mechanisms for smooth and secure handling. Lever-lock type ensures stable handling by constant pinching force when locked, and enhances work efficiency.

Lever-Lock Type Manual Wand

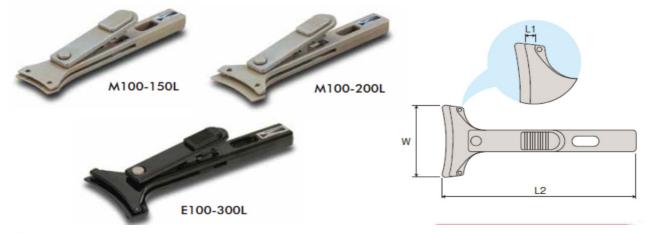
Lever-Lock Series / Conductive Lever-Lock Series

PAT.P

- Utilizing leverage, stable pinching force is sustained with less power.
- Lock mechanism only requires the force to support the weight of wafer after pinching.
- Release from labor to keep holding unlike manual wand.
- Ensures stable gripping and safe and efficient handling.
- 2-point contact of pinching face minimizes contamination to wafer.
- Made of PEEK having superior strength, heat resistance and chemical resistance.
- Conductive lever-lock series is made of conductive PEEK blended with nano-carbon. Effective as antistatic measures for wafer handling.

Code	Description	Material		Size (n	Weight	
Code	de Description Material		8	L1	L2	(g)
M100-150L	6" lever-lock manual wand		40	3	185	71
M100-200L	8" lever-lock manual wand	PEEK	55	3	180	72
M100-300L	12" lever-lock manual wand		75	8	180	77
E100-150L	6" conductive lever-lock manual wand	conductive PEEK	40	3	185	71
E100-200L	8" conductive lever-lock manual wand	conductive PEEK	55	3	180	72
E100-300L	12" conductive lever-lock manual wand	conductive PEEK	75	8	180	77

*E100 type: PEEK without filler is used for support to strengthen.



This is made for silicon wafer. Please fully evaluate prior to use.

Manual Wand

L Series PAT.P

- 2-point contact minimizes contamination to wafer.
- Eliminates the potential of damage to wafer unlike conventional metal tweezers.
- Proprietary wafer stopper minimizes contact to wafer.
- Adhesive and metal free body can be cleaned and is kept clean.
- Material suitable for application is available.

Code	Description	Material	Size (mm)			Weight
Code	Description	iviateriai	W	L1	L2	(g)
M100-100	4" Wand		16	4	146	30
M100-125	5" Wand		32	5	148	31
M100-150	6" Wand		37	6	147	31
M100-200	8" Wand	PEEK	37	8	147	32
M110-100	4" Wand		16	4	146	31
M110-125	5" Wand	A	32	5	148	32
M110-150	6" Wand		37	6	147	33
M110-200	8" Wand	PPS	37	8	147	33
E100-100	4" Wand		16	4	146	31
E100-125	5" Wand		32	5	148	33
E100-150	6" Wand		37	6	147	34
E100-200	8" Wand	conductive PEEK	37	8	147	34



M100-100

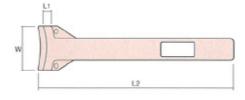
M100-125

M100-150

^{*}PPS (polyphenylene sulfide)



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Manual Wand for High Temperature Application (made on order)

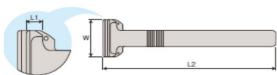
H Series PAT.P

- Developed the method to securely bond SUS304 to Vespel. Thus, made pinching part thinner to prevent contact the adjoining wafre.
- Stable performance even under high temperature (288°C). And effective to prevent particle generation.

Code	Description	Material	9	Weight		
Code	Description	Material	W	L1	L2	(g)
M800-200N	6", 8" normal type	Vesnel i CLIC	35	7	154	47
M800-200S	6", 8" scoop type	Vespel + SUS	35	7	159	47

^{*}Vespel is a registered trademark of U.S. DuPont.







Oh, this is convenient **Tabletop Stand for Manual** Wand (Material: Acrylic) Code No.: 670





This is made for silicon wafer. Please fully evaluate prior to use.

^{*}PEEK (polyether ether ketone)